

## ABSTRACT

A raised solder-mask-defined (SMD) pad configured for receiving a solder ball on a laminate electronic circuit board and a method of creating the raised SMD pad on a laminate electronic circuit board. The method may comprise forming a base bump, covering the base bump with a conductive bump layer and layering a surrounding material over an extended edge of the conductive bump layer. The surrounding material is patterned to expose a pad face and of a portion of the sides of the conductive bump layer, such that the pad face is disposed above the surface of the surrounding material. The surrounding material may be patterned by a photolithography operation or alternatively, a laser-drill operation.